



PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No: 10/621,963 Docket No: 2011123
Filing Date: 07/16/2003 Applicant: Chung Hsien HSIN
Examiner: DUONG, HUANG V Art Unit: 2835
Title: IMAGE SENSOR AND METHOD FOR MANUFACTURING THE SAME

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL OF AMENDMENT

1. Transmitted herewith is a response to an office action for this application prepared and submitted by the Applicant.
2. Applicant is entitled to Small Entity Status.
3. The proceedings herein are for a patent application and the provisions of 37 CFR 1.136 apply. Applicant believes that no extension of time is required. However, a conditional petition is hereby made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.
4. No fee is required at this time.
5. Certificate of Mailing (37 CFR 1.8a): I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Arlington, VA 22313-1450.

Respectfully submitted,


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SAME
To: THE ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action dated 11/29/2004, Applicant submits the
5 following arguments.

ARGUMENTS

1. Claims 1 to 6 are rejected under 35 USC §103(a) as being unpatentable
Hsin (10621962).

Applicant thinks that it is true that Hsin does not disclose that an image
10 sensor includes a substrate, a photosensitive chip, a plurality, a frame layer, and a
transparent layer. Wherein the transparent layer is fixed and is encapsulated by the
frame layer such that the photosensitive chip may receive optical signals passing
the transparent layer.

According to the examiner's opinion, please refer to the 962,patent, which is
15 shown an image sensor module having a substrate, a photosensitive chip, a
plurality of wires, a frame layer, a transparent layer, and lens. Wherein the frame
layer is mounted to the substrate to surround the photosensitive chip, an inner
edge of the frame layer is formed with an internal thread from top to bottom, and
the transparent layer is encapsulated by the frame layer.

20 Further, the filing date of the 962, patent and this application are same in
7/16/2003, thus, the 962, patent do not motivate the Applicant to finish this
application.

Then, the present is an image sensor, which includes a substrate, a